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Attorney Docket No. 9180-30

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
In re: Jong-Rong Jan et al.
Application No.: 10/780,529
Filed: February 17, 2004
For: *Methods Of Selectively Bumping Integrated Circuit Substrates And Related Structures*

Confirmation No.: 1502
Group Art Unit: 2818
Examiner: Chuong A. Luu
Date: November 10, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §1.97(c)**

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(c), before final Office Action or Allowance, whichever is earlier.

In accordance with the requirements of 37 C.F.R. § 1.97(c)(2), a check for the \$180.00 fee specified in 37 C.F.R. § 1.17(p) is enclosed. This amount is believed to be correct. However, the Commissioner is authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. §1.56 and Section 609 of the MPEP.

Respectfully submitted,


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Sheena L. Donnelly

NOV 14 2005

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(use as many sheets as necessary)

		Complete if Known		
		Application Number	10/780,529	
		Filing Date	February 17, 2004	
		First Named Inventor	Jong-Rong Jan	
		Group Art Unit	2818	
		Examiner Name	Chuong A. Luu	
Sheet	1	of	7	Attorney Docket Number

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Sheet	2	of	7	Attorney Docket Number	9180-30
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		<i>Complete if Known</i>			
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		Group Art Unit	2818		
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Examiner Name				Chuong A. Luu	
Attorney Docket Number				9180-30	

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Substitute form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Complete if Known		
Sheet	5	of	7	Application Number	10/780,529	
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				First Named Inventor	Jong-Rong Jan	
				Group Art Unit	2818	
				Examiner Name	Chuong A. Luu	
				Attorney Docket Number	9180-30	

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Examiner Signature		Date Considered	
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Substitute form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Complete if Known	
Sheet	4	of	7	Application Number	10/780,529
				Filing Date	February 17, 2004
				First Named Inventor	Jong-Rong Jan
				Group Art Unit	2818
				Examiner Name	Chuong A. Luu
				Attorney Docket Number	9180-30

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